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T. L. W. H.  
5-14-99  
**PATENT**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of )

Group Art Unit: 2822

Shunpei YAMAZAKI et al. )

Examiner: Maria Guerrero

Serial No.: 09/118,010 )

Filed: July 17, 1998 )

For: SEMICONDUCTOR DEVICE,  
METHOD OF FABRICATING SAME,  
AND ELECTROOPTICAL DEVICE )

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on May 3, 1999.

*Kristen M. Johnson*

**AMENDMENT**

Assistant Commissioner for Patents  
Washington, D. C. 20231

**RECEIVED**

**MAY 13 1999**

Sir:

TECHNOLOGY CENTER 2800

In response to the Office Action mailed December 1, 1998, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Please cancel claims 9 and 10 without prejudice or disclaimer and amend claims 1 and 5 as follows:

1. (Amended) A semiconductor device comprising:

a [filmy] resinous substrate having an uneven surface;

a resinous layer provided on said uneven surface of said [filmy] resinous substrate and having

a planarized surface; and

A1 SubC1

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